

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

CLAIMS LISTING (claims 1-12, 13-20, 22-33, 34-36)

**Claims 1-12:** (*Canceled*).

**Claim 13 (Currently Amended):** A display device, comprising:

a mold frame, including a series of optical sheets;

a bottom chassis assembled to said mold frame, the bottom chassis defining a means for dissipating electromagnetic interference (EMI) coupled thereto;

a top chassis assembled to said mold frame;

a display panel positioned between said bottom chassis and said top chassis;

a printed circuit board (PCB) having top and bottom major surfaces and being

connected to said display panel, the PCB being disposed below the bottom chassis such that its bottom surface is closer to the bottom chassis than is the top surface of the PCB; and,

one or more -a- grounding protrusions formed on to protrude from the bottom surface an upper surface of said PCB and coupled to an electrical ground of the PCB,

wherein the one or more grounding protrusions protrude beyond the bottom surface of the

PCB by a protrusion distance that exceeds heights of is protruded higher than any other components formed on the bottom surface of the PCB, and the one or more ground protrusions are is disposed in contact with the bottom chassis so as to thereby couple at least some of EMI produced in the PCB to the bottom chassis.

**Claim 14 (Previously Presented):** The display device according to Claim 13, wherein said mold frame accommodates a lamp assembly and a reflector.

**Claim 15 (Previously Presented):** The display device according to Claim 14, wherein said display panel is positioned onto said optical sheets.

**Claim 16 (Previously Presented):** The display device according to Claim 15, wherein said PCB is connected to said display panel via a tape carrier package (TCP), and fixed to said bottom chassis by a fixing means.

**Claim 17 (Currently Amended):** The display device according to Claim 16, wherein said one or more grounding protrusions are is formed on said PCB in areas of the bottom surface of the PCB where a signal transmission patterns are is not formed.

**Claim 18 (Previously Presented):** A display device, comprising:

a chassis;

a display panel assembled with the chassis;

a printed circuit board (PCB) connected to the display panel, the PCB being disposed below the chassis, the PCB having top and bottom major surfaces, where said bottom major surface is closer to the chassis than is the top major surface of the PCB; and,

one or more a ground protrusions protruding from the bottom major surface formed on an upper surface of the PCB,

wherein the chassis is disposed between the display panel and the PCB and the one or more ground protrusions have protrusion heights greater is protruded higher than other heights of any other components formed on the upper bottom surface of the PCB and one or more of the ground protrusions are is disposed to be in contact with a lower surface of the chassis.

**Claim 19 (Currently Amended):** The display device of Claim 18, wherein the PCB comprises a grounding pattern, and the one or more ground protrusions are electrically coupled to being protruded from the grounding pattern.

**Claim 20 (Previously Presented):** The display device of Claim 19, wherein the PCB further comprises a driving integrated circuit (IC) and a signal transmission pattern.

**Claim 21: (Canceled).**

**Claim 22 (Previously Presented):** The display device of Claim 19, wherein the PCB is attached on the chassis.

**Claim 23 (Previously Presented):** The display device of Claim 22, wherein the PCB has a screw hole and is attached to the chassis by a screw.

**Claim 24 (Previously Presented):** The display device of Claim 23, wherein the screw hole is formed on a corner of the PCB.

**Claim 25 (Currently Amended):** The display device of Claim 22, wherein one or more of the ground protrusions are in direct contact with the chassis.

**Claim 26 (Previously Presented):** The display device of Claim 18, further comprising a tape carrier package (TCP) coupled between the display panel and the PCB.

**Claim 27 (Previously Presented):** The display device of Claim 18, further comprising a mold frame assembled with the chassis.

**Claim 28 (Previously Presented):** The display device of Claim 18, further comprising a back-light assembly unit.

**Claim 29 (Previously Presented):** The display device of Claim 28, wherein the backlight assembly unit comprises a lamp, a reflector and an optical sheet.

**Claim 30 (Previously Presented):** The display device of Claim 29, wherein the backlight assembly unit further comprises a light guiding plate.

**Claim 31 (Previously Presented):** The display device of Claim 19, wherein the PCB further comprises a via hole.

**Claim 32 (Currently Amended):** A display device, comprising:

- a mold frame, including a series of optical sheets;
- a bottom chassis assembled to said mold frame;
- a top chassis assembled to said mold frame;
- a display panel positioned between said bottom chassis and said top chassis;

a printed circuit board (PCB) disposed below and connected to said bottom chassis, the PCB having top and bottom major surfaces, where said bottom major surface is closer to the bottom chassis than is the top major surface of the PCB; and [I,J]

one or more a- grounding protrusions extending from the bottom major surface formed on an upper surface of said PCB,

wherein one or more of the ground protrusions are directly is connected to the bottom chassis.

**Claim 33 (Currently Amended):** A display device, comprising:

a chassis;

a display panel assembled with the chassis;

a printed circuit board (PCB) disposed below the chassis and connected to the display panel, the PCB having top and bottom surfaces, where said bottom surface is closer to the chassis than is the top surface of the PCB; and [I,J]

one or more a ground protrusions protruding from the bottom formed on a surface of the PCB, wherein

the chassis is disposed between the display panel and the PCB,

the ground protrusions protrude beyond the bottom surface further is protruded higher than any other components formed on the bottom surface, and

the ground protrusions protrude [-s] toward and make [-s] contact with the chassis.

**Claim 34 (New):** The display device of Claim 13 wherein:

a plurality of said grounding protrusions are positioned under an active device of the PCB, where the active device protrudes from the top surface of the PCB.

**Claim 35 (New):** The display device of Claim 13 wherein:

said grounding protrusions include a UV-cured conductive material.

**Claim 36 (New):** The display device of Claim 13 wherein:

said grounding protrusions protrude through a solder resist layer.

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